Date: 03/27/20
Attendees: Dan, Eelco, Jawad, Kevin, Manoj, Mark, Paul, Scott, Ali, Sean, DJ, Reza, Rita, Jia, Manuel, Tawfik, Sam, David, Jinshui, Bapi, JP

Agenda:

1. ODSA Session at Virtual Summit (panels, short sessions)
2. Eelco - ASE
3. Jia Ning - FB - Modularity Initiative

1. Modularization Task Group (Jia)
    a. Kicking off an effort inside OCP, inviting participation
    b. Jia Ning, John Stuewe, Siamak Tavallei for questions
    c. Is there a roadmap for deliverables, none yet in scoping stage
    d. DJ - aim to disseminate modules to new applications e.g. ODSA using OCP NIC3.0 as a form factor, gather requirements across groups to module owners
2. ASE (notes thanks to Jawad)
    a. Eelco gave a talk about the packaging perspective and ASE's interest in ODSA.
    b. -Background of ASE includes assembly and test and more of system integration (USI) which is a growing business.
    c. -Now that Moores law is slowing, advance packaging is where the renewed innovations are.
    d. -IC Packaging bridges the gap in Si and PCB in terms of the technology.
    e. -Die disaggregation and partitioning has been happening in more recent IC technologies for cost and performance reasons.
    f. -Eelco explained packaging processes for SIP/MCM, 2.5DTSV, and FOCoS.
    g. -FOCoS cost can be lower than the silicon interposer based solutions for HBM.
    h. -Yields of FOCoS are comparable to CoWoS.
    i. -Call to Action: Virtual prototyping of PoC for packaging using BoW footprint standardization in the CDX group. More details to follow at a late date.
3. OCP Agenda
    a. Short talks -
    b. Panels
        i. Rita prefers Friday option
        ii. Manuel
    c. We’re going to aim for live audiences - Friday 4/3 and 4/10 if the schedule works for the virtual summit organizers.